

### **PNP Silicon AF Transistors**

- For AF driver and output stages
- High collector current
- Low collector-emitter saturation voltage
- Complementary types: BCP54 ... BCP56 (NPN)
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101





Туре	Marking	Pin Configuration			Package
BCP51	*	1=B	2=C	3=E	SOT223
BCP51-16	*	1=B	2=C	3=E	SOT223
BCP52-16	*	1=B	2=C	3=E	SOT223
BCP53-10	*	1=B	2=C	3=E	SOT223
BCP53-16	*	1=B	2=C	3=E	SOT223

\* Marking is the same as type-name

<sup>1</sup>Pb-containing package may be available upon special request



#### **Maximum Ratings**

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	V <sub>CEO</sub>		V	
BCP51		45		
BCP52		60		
BCP53		80		
Collector-base voltage	V <sub>CBO</sub>			
BCP51		45		
BCP52		60		
BCP53		100		
Emitter-base voltage	V <sub>EBO</sub>	5		
Collector current	I <sub>C</sub>	1	A	
Peak collector current, $t_p \le 10 \text{ ms}$	I <sub>CM</sub>	1.5		
Base current	I <sub>B</sub>	100	mA	
Peak base current	/ <sub>BM</sub>	200		
Total power dissipation-	P <sub>tot</sub>	2	W	
$T_{S} \leq 120^{\circ}C$				
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-65 150		
Thermal Resistance				
Parameter	Symbol	Value	Unit	
Junction - soldering point <sup>1)</sup>	R <sub>thJS</sub>	≤ <b>15</b>	K/W	

<sup>1</sup>For calculation of  $R_{\rm thJA}$  please refer to Application Note Thermal Resistance



Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	1 1			1	
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>				V
<i>I</i> <sub>C</sub> = 10 mA, <i>I</i> <sub>B</sub> = 0 , BCP51		45	-	-	
<i>I</i> <sub>C</sub> = 10 mA, <i>I</i> <sub>B</sub> = 0 , BCP52		60	-	-	
<i>I</i> <sub>C</sub> = 10 mA, <i>I</i> <sub>B</sub> = 0 , BCP53		80	-	-	
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>				
/ <sub>C</sub> = 100 μA, / <sub>E</sub> = 0 , BCP51		45	-	-	
/ <sub>C</sub> = 100 μA, / <sub>E</sub> = 0 , BCP52		60	-	-	
/ <sub>C</sub> = 100 μA, / <sub>E</sub> = 0 , BCP53		100	-	-	
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	5	-	-	]
<i>I</i> <sub>E</sub> = 10 μA, <i>I</i> <sub>C</sub> = 0	· · /				
Collector-base cutoff current	I <sub>CBO</sub>				μA
$V_{\rm CB} = 30 \text{ V}, I_{\rm E} = 0$		-	-	0.1	
$V_{\rm CB}$ = 30 V, $I_{\rm E}$ = 0 , $T_{\rm A}$ = 150 °C		-	-	20	
DC current gain <sup>1)</sup>	h <sub>FE</sub>				-
I <sub>C</sub> = 5 mA, V <sub>CE</sub> = 2 V		25	-	-	
<i>I</i> <sub>C</sub> = 150 mA, <i>V</i> <sub>CE</sub> = 2 V, BCP51		40	-	250	
<i>I</i> <sub>C</sub> = 150 mA, <i>V</i> <sub>CE</sub> = 2 V, BCP53-10		63	100	160	
<i>I</i> <sub>C</sub> = 150 mA, <i>V</i> <sub>CE</sub> = 2 V, BCP51-16BCP53-16		100	160	250	
<i>I</i> <sub>C</sub> = 500 mA, <i>V</i> <sub>CE</sub> = 2 V		25	-	-	
Collector-emitter saturation voltage1)	V <sub>CEsat</sub>	-	-	0.5	V
I <sub>C</sub> = 500 mA, I <sub>B</sub> = 50 mA					
Base-emitter voltage <sup>1)</sup>	V <sub>BE(ON)</sub>	-	-	1	1
I <sub>C</sub> = 500 mA, V <sub>CE</sub> = 2 V	( - )				
AC Characteristics					
Transition frequency	f <sub>T</sub>	-	125	-	MHz
<i>I</i> <sub>C</sub> = 50 mA, <i>V</i> <sub>CE</sub> = 10 V, <i>f</i> = 100 MHz					

**Electrical Characteristics** at  $T_A = 25^{\circ}$ C, unless otherwise specified

<sup>1</sup>Pulse test: t < 300 $\mu$ s; D < 2%



## **DC current gain** $h_{\text{FE}} = f(I_{\text{C}})$

*V*<sub>CE</sub> = 2 V







#### **Collector-emitter saturation voltage**

 $I_{\rm C} = f(V_{\rm CEsat}), h_{\rm FE} = 10$ 



Collector cutoff current  $I_{CBO} = f(T_A)$  $V_{CBO} = 30 \text{ V}$ 





# **Transition frequency** $f_{\rm T} = f(I_{\rm C})$

*V*<sub>CE</sub> = 10 V



**Permissible Pulse Load**  $R_{\text{thJS}} = f(t_p)$ 



Total power dissipation  $P_{tot} = f(T_S)$ 



# Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$ 





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